

REMARKS

Claims 1 and 4-19 are pending. Claims 2 and 3 are cancelled herein without prejudice or disclaimer. Claims 1, 6, 10, 15 and 16 are amended herein. Support for the amendments is found in original claims 2 and 3 and as detailed below.

Applicants' Response to the Claim Objections

The claims are objected to because they include references to figures.

In response thereto, applicants have removed the references to figures from the claims.

Applicants' Response to the Claim Rejections under 35 U.S.C. §102

Claims 1, 2, 10, 11 and 16 are rejected under 35 U.S.C. §102(b) as being anticipated by *Soga et al.* (WO 02/49797).

Applicants have herein incorporated the feature of claim 3 into parent claims 1 and 10. In light of this amendment, applicants respectfully submit that the rejection is now moot.

Applicants' Response to the Claim Rejections 35 U.S.C. §103

Claims 1-12 and 14-19 are rejected under 35 U.S.C. §103(a) as being unpatentable over *Ueda et al.* (JP H11-284111) in view of *Jin et al.* (US 6,326,685).

In response thereto, applicants respectfully submit that the present invention as now claimed is not obvious in light of the combination of Ueda and Jin for at least the reason that the

combination does not provide for all the features of the claims, nor is there a reason prompting a skilled artisan to modify the combination of Ueda and Jin so as to derive the claimed invention.

Specifically, the combination at least fails to provide for the features of parent claims 1 and 10 that the content of Sn in the first brazing layer is at least 1 mass % and not more than 13 mass % and the content of Cu is the highest and the content of Sn is the second highest in the first brazing layer.

The rejection cites to Ueda as disclosing brazing a copper layer to a molybdenum layer using a brazing material and acknowledges that Ueda does not disclose the claimed Sn-Cu alloy of the brazing layer. For this feature, the rejection cites to Jin as disclosing separate alloys at col. 4, lines 35-37 of Sn-Cu alloys of Cu-Zn-Sn (30-45% Zn, 0-20% Sn, balance Cu), and Cu-Sn (20-30% Sn, balance Cu).

Jin does not disclose an Sn-Cu alloy which has a 13 mass % of Sn. The Cu-Sn only alloy must have at least 20% and the alloy teaching 0-20% Sn must include at least 30% Zn. Further, there is no reason prompting a skilled artisan to reduce the amount of Sn by 7 mass % in the Cu-Sn only alloy.

Wherefore, assuming a combination of Ueda and Jin where to be made, the combination cannot result in the feature of the claims that the content of Sn in the first brazing layer is at least 1 mass % and not more than 13 mass % and the content of Cu is the highest and the content of Sn is the second highest in the first brazing layer.

Claims 4 and 13 are rejected under 35 U.S.C. §103(a) as being unpatentable over Ueda et al. (JP H11-284111) in view of Jin et al. (US 6,326,685), further in view of Sakata et al. (US 2001/0008703).

Applicants respectfully submit that by addressing the rejections of parent claims 1 and 10 as detailed above, likewise these rejections are addressed by nature of their dependency.

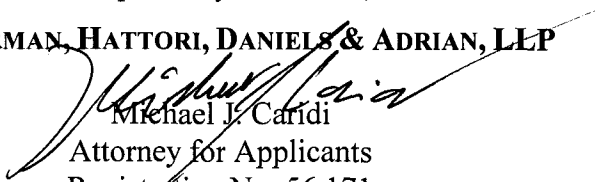
In view of the aforementioned amendments and accompanying remarks, Applicants submit that the claims, as herein amended, are in condition for allowance. Applicants request such action at an early date.

If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

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